

BAT54WS-Q1

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BAT54WS-Q1

200mA Surface Mount Small Signal Schottky Diodes-30V

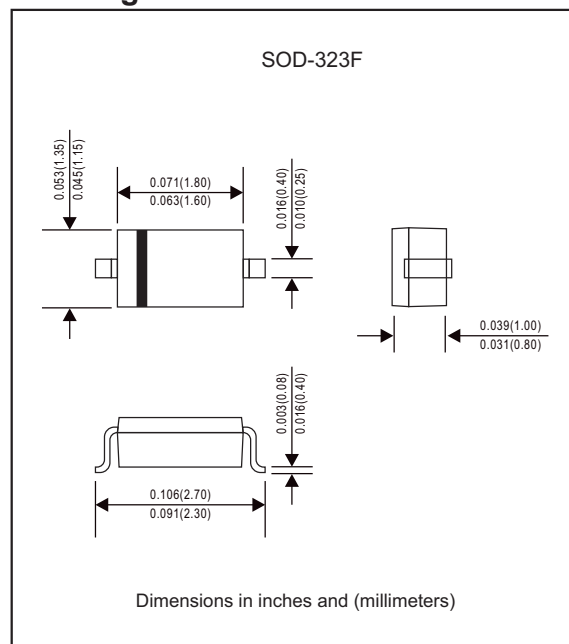
Features

- Low current rectification and high speed switching
- Small surface mount type
- Up to 200mA current capability
- Low forward voltage drop (0.35V typ. @ $I_F=10\text{mA}$)
- Silicon epitaxial planar chip, metal silicon junction
- High speed ($t_{rr} < 5\text{ ns}$)
- Lead-free parts meet RoHS requirements
- Qualified to AEC-Q101 standards for high reliability
- Suffix "-H" indicates halogen free parts, ex. BAT54WS-Q1-H

Mechanical data

- Epoxy:UL94-V0 rated flame retardant
- Case : Molded plastic, SOD-323F
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity : Indicated by cathode band
- Mounting Position : Any
- Weight : Approximated 0.005 gram

Package outline



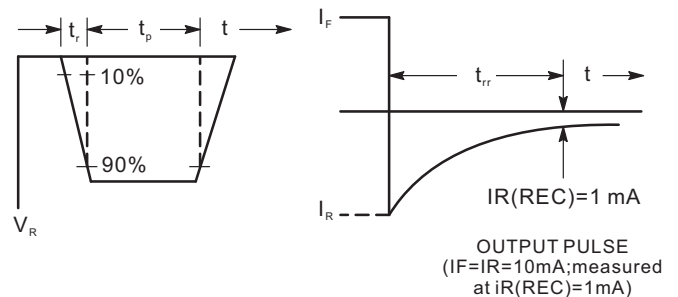
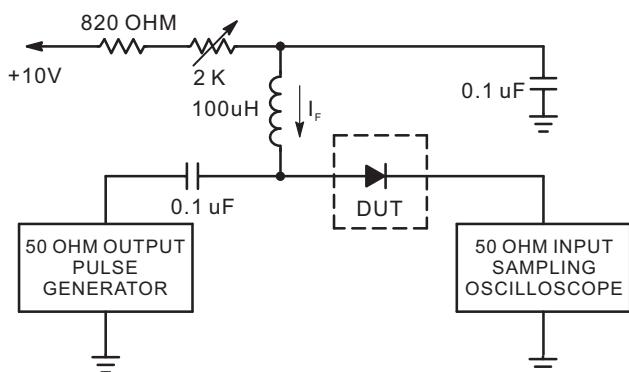
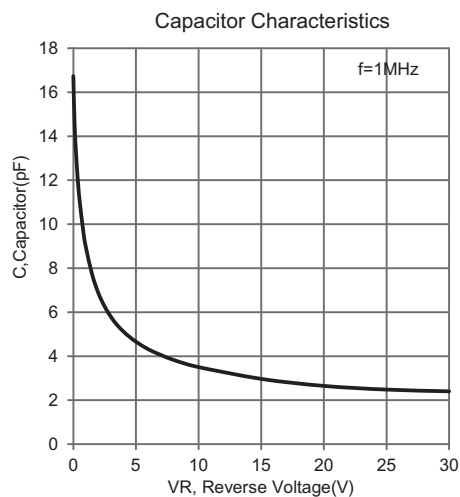
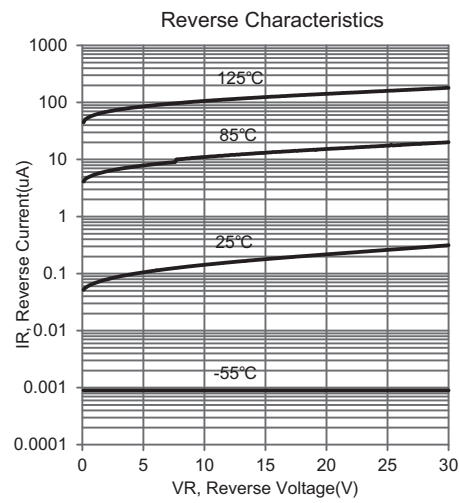
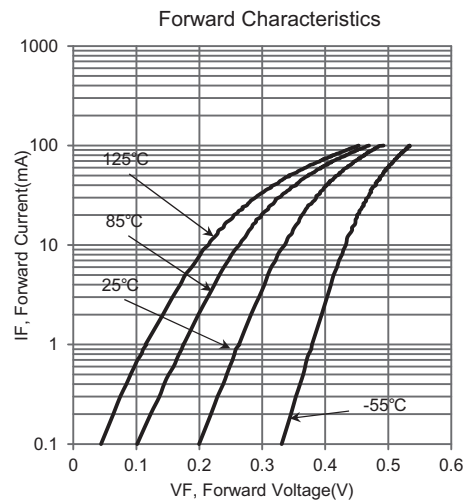
Maximum ratings (AT $T_A=25^\circ\text{C}$ unless otherwise noted)

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Repetitive peak reverse voltage		V_{RRM}			30	V
Reverse voltage		V_R			30	V
Repetitive peak forward current		I_{FRM}			300	mA
Non-repetitive peak forward current	$t < 1.0\text{ s}$	I_{FSM}			600	mA
Forward current		I_F			200	mA
Power dissipation	Mounted on FR-5 board at $T_A=25^\circ\text{C}$	P_D			200	mW
Thermal resistance	Junction to ambient	$R_{\theta JA}$		635		$^\circ\text{C/W}$
Operating junction temperature range		T_J	-55		+125	$^\circ\text{C}$
Storage temperature range		T_{STG}	-55		+125	$^\circ\text{C}$

Electrical characteristics (AT $T_A=25^\circ\text{C}$ unless otherwise noted)

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Forward voltage	$I_F = 0.1\text{ mA}$	V_F		0.220	0.240	V
	$I_F = 1\text{ mA}$	V_F		0.290	0.320	V
	$I_F = 10\text{ mA}$	V_F		0.350	0.400	V
	$I_F = 30\text{ mA}$	V_F		0.410	0.500	V
	$I_F = 100\text{ mA}$	V_F		0.520	1.000	V
Reverse current	$V_R = 25\text{ V}$	I_R		0.5	2.0	μA
Total capacitance	$V_R = 1\text{ V}, f = 1\text{ MHz}$	C_T			10.0	pF
Reverse recovery time	$I_F = I_R = 10\text{ mAdc}, I_{R(REC)} = 1.0\text{ mAdc}$	t_{rr}			5.0	ns

Rating and characteristic curves for each diode (BAT54WS-Q1)



- Notes :
1. A2.0 Kohm variable resistor adjusted for a forward Current (I_F) of 10mA.
 2. Input pulse is adjusted so $I_R(\text{peak})$ is equal to 10 mA.
 3. $t_p \gg t_{rr}$.

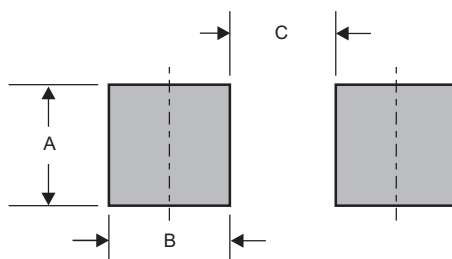
Recovery Time Equivalent Test Circuit

BAT54WS-Q1**Pinning information**

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

Marking

Type number	Marking code
BAT54WS-Q1	JV,S1

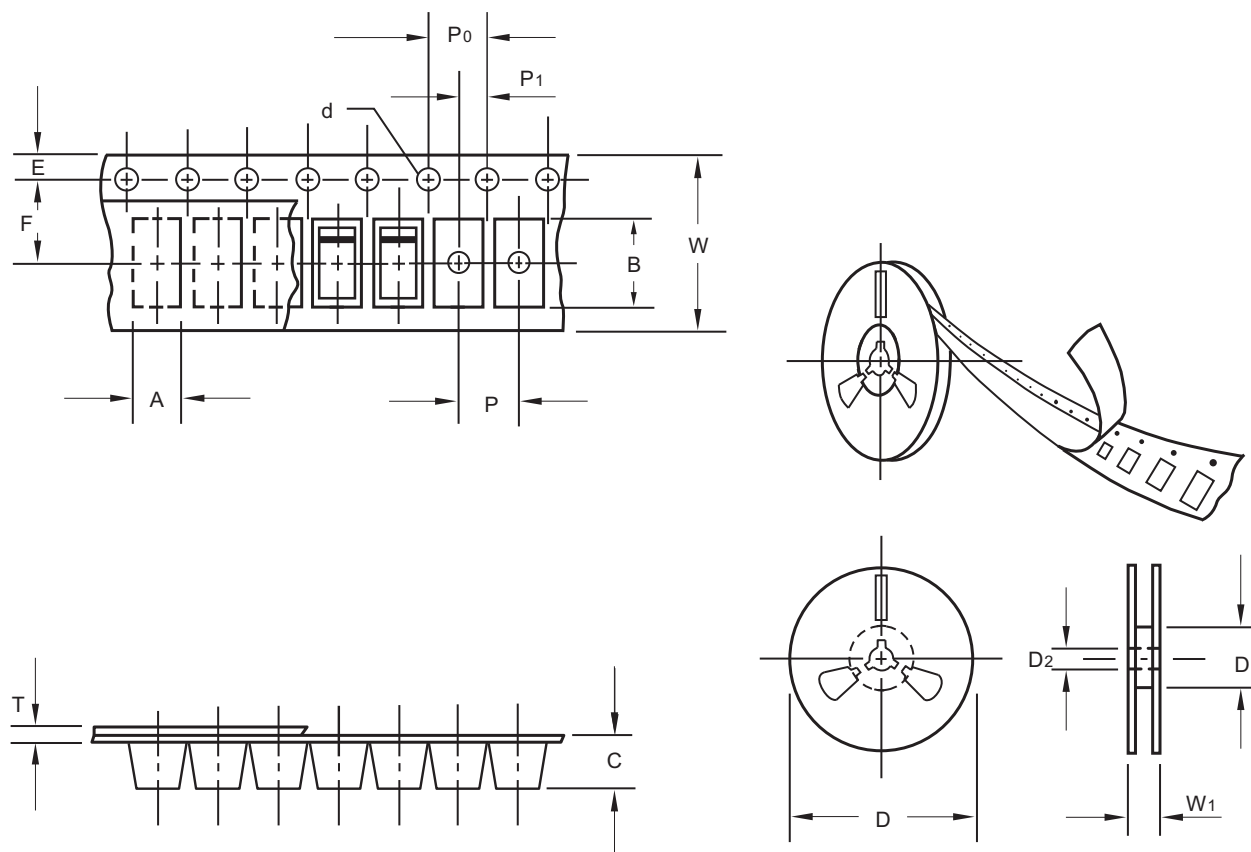
Suggested solder pad layout

Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SOD-323F	0.033 (0.83)	0.025 (0.63)	0.063 (1.60)

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Packing information



unit:mm

Item	Symbol	Tolerance	SOD-323F
Carrier width	A	0.1	1.46
Carrier length	B	0.1	2.95
Carrier depth	C	0.1	1.25
Sprocket hole	d	0.1	1.50
13" Reel outside diameter	D	2.0	-
13" Reel inner diameter	D1	min	-
7" Reel outside diameter	D	2.0	178.00
7" Reel inner diameter	D1	min	62.00
Feed hole diameter	D2	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	3.50
Punch hole pitch	P	0.1	4.00
Sprocket hole pitch	P0	0.1	4.00
Embossment center	P1	0.1	2.00
Overall tape thickness	T	0.1	0.23
Tape width	W	0.3	8.00
Reel width	W1	1.0	11.40

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

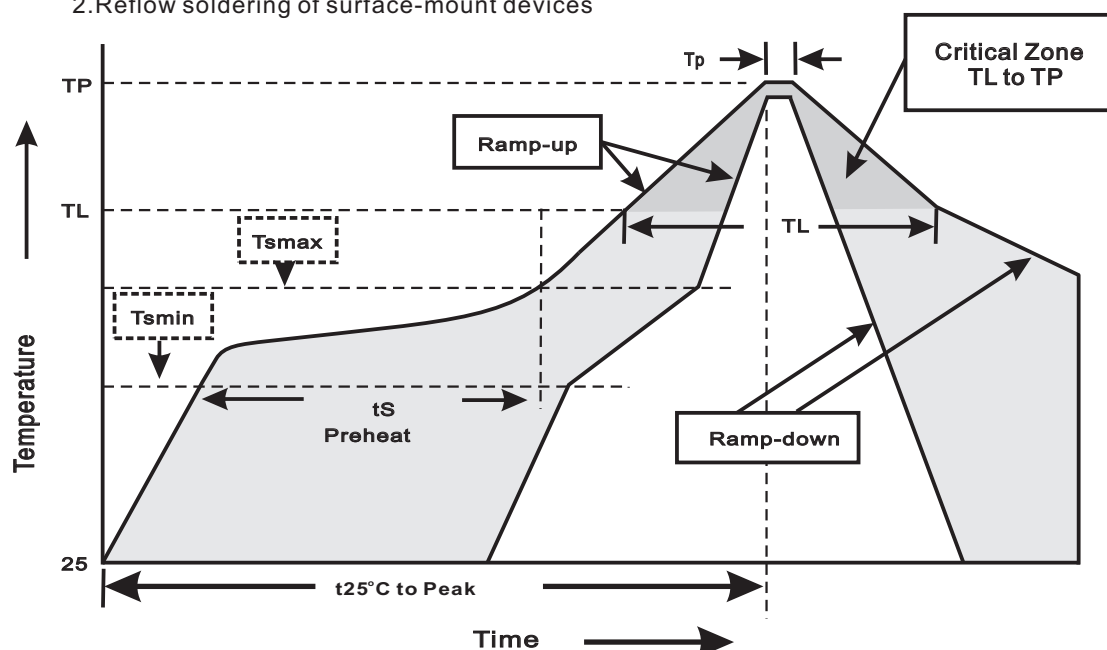
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Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA, (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SOD-323F	7"	3,000	4.0	30,000	183*123*183	178	382*257*387	240,000	8.0

Suggested thermal profiles for soldering processes

- 1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
- 2.Reflow soldering of surface-mount devices



3.Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(T _L to T _P)	<3°C/sec
Preheat -Temperature Min(T _{smmin}) -Temperature Max(T _{smmax}) -Time(min to max)(t _s)	150°C 200°C 60~120sec
T _{smmax} to T _L -Ramp-upRate	<3°C/sec
Time maintained above: -Temperature(T _L) -Time(t _L)	217°C 60~260sec
Peak Temperature(T _P)	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(t _P)	10~30sec
Ramp-down Rate	<6°C/sec
Time 25°C to Peak Temperature	<6minutes

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High reliability test capabilities

Item Test	Conditions	Reference
1. MSL Preconditioning	24hr bake@125°C+168hrs@85°C /85%RH+3xIR@260°C+1flux immersion+alcohol+DI H2O rinse	JESD22-A113
2. Operation Life	Ta=25°C, Rated Current (Io=Io max.) Test Duration: 1000hrs	MIL-STD-750E METHOD 1027.3
3. High Temperature Reverse Bias	80% Rated VR (Tj=Tj max.) Test Duration: 1000hrs	JESD22-A108
4. High Temperature Storage Life	Ta=125°C Test Duration: 1000hrs	JESD22 A-103
5. Temperature Cycle	-55°C(15min) to 150°C(15min) Test Cycles: 1000cycles	JESD22 A-104
6. Autoclave	P=2atm Ta=121°C RH=100% Test Duration: 96hrs	JESD22 A-102
7. Intermittent Operational Life	Ta=25°C, On/Io Max. 2min, Off/2min, Test Cycles: 15000cycles	MIL-STD-750E METHOD 1037
8. Solderability	245±5°C for 5sec	J-STD-002
9. Moisture Resistance	Ta=85°C/85% Relative humidity Test Duration: 1000hrs	MIL-STD-750E METHOD 1021.2
10. Resistance To Solder Heat	260±5°C for 10sec	JESD22 B-106
11. High Temperature High Humidity Reverse Bias	Ta=85°C, 85%RH, with device reverse biased at 80% of rated breakdown voltage up to a maximum of 100V or limit of chamber Test Duration: 1000hrs	JESD22-A101